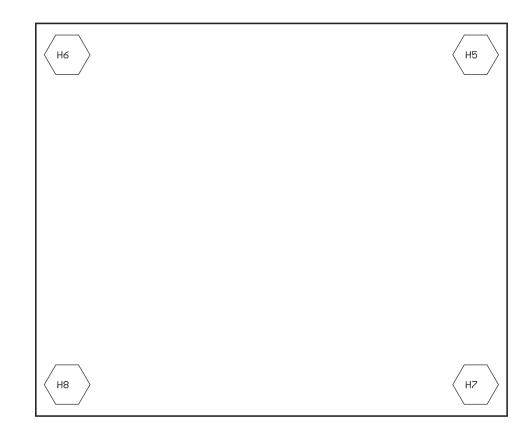


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10545	REV:	SVN REV:	: Not In VersionControl
IGNORE ->				
PLOT NAME = Top Assembly Drawing	GENERATED : 4/20/2	2015 4:04:42	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10545	REV:	SVN REV: Not In VersionControl		
	IGNORE ->				
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/20/2	2015 4:04:43	PM TEXAS INSTRUMENTS		

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